

TOSHIBA CORPORATION

Toshiba Electronic Devices & Storage Corporation

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Date: October 25, 2017

Ref. No.: O-HKN-17-00060E

To: **DIGI KEY ELECTRONICS**

Dear Sir/ Madam:

Change in Specification of Packing Tray

We greatly appreciate your continued business.

This is to notify our customers of our plan to change wafer fab of our products supplied to you.

Full details of the planned change are given in the following page.

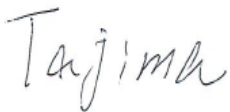
If you have any questions or inquiry regarding this change, please inform our Sales representatives nearest you as soon as possible.

We appreciate your understanding and cooperation.

Yours faithfully,

Reviewed by H. Kashima

Approved by I.Tajima, Manager



Quality Reliability Service Group Oita Office

Quality & Reliability Engineering Dept.

Toshiba Electronic Devices & Storage Corporation

Change in Specification of Packing Tray

1. Product to be Affected : 256 part types (See the attached file for affected part numbers)

2. Description of Change : - Unification of packing tray types
From Toshiba's tray and JEDEC-compliant tray
To JEDEC-compliant tray

3. Reason of Change : To unify packing tray types and reduce wastes

4. Scheduled Date of Change : With your approval from April 2018 onward

5. Remark : If you have any questions or requests regarding this change, please inform our Sales representatives nearest you as soon as possible.

Notice of Approval (For customer use)

Ref. No.: O-HKN-17-00060E >

- We approve the above change.
- We approve the above change with the following conditions.
- We disapprove the above change for the following reasons.

[Specify the conditions/ reasons]

Date : _____

Company : _____

Department : _____

Approved by : _____